

### Description

LNCQ28PS01WW is a MOCVD fabricated 660nm band wavelength laser diode with multi quantum well structure, using TO-56 CAN package to ensure versatile use.

### Features

- Wavelength: 661 nm (typ.)
- High output power and temperature: 100 mW, Max+85°C (CW)  
300 mW, Max+85°C (pulse)  
350 mW, Max+75°C (pulse)
- Package: TO-56 CAN

### Applications

- Optical disk drive
- Sensing
- Analysis
- Measurement
- Agriculture
- Other industrial use



### Absolute Maximum Ratings

Item	Symbol	Value	Unit	Condition
Output power	Po	100	mW	CW
		300	mW	pulse <sup>1)</sup>
		350	mW	pulse <sup>2)</sup>
Reverse voltage	Vr	1.5	V	CW
Operating case temperature	Tc	-10 to +85	°C	CW
		-10 to +85	°C	pulse <sup>1)</sup>
Storage temperature	Tstg	-40 to +85	°C	

Note) 1) Pulse width  $\leq 40$ ns, duty  $\leq 33\%$

2) Pulse width  $\leq 40$ ns, duty  $\leq 33\%$  Operating case temperature condition: -10~+75°C

### Electrical and Optical Characteristics

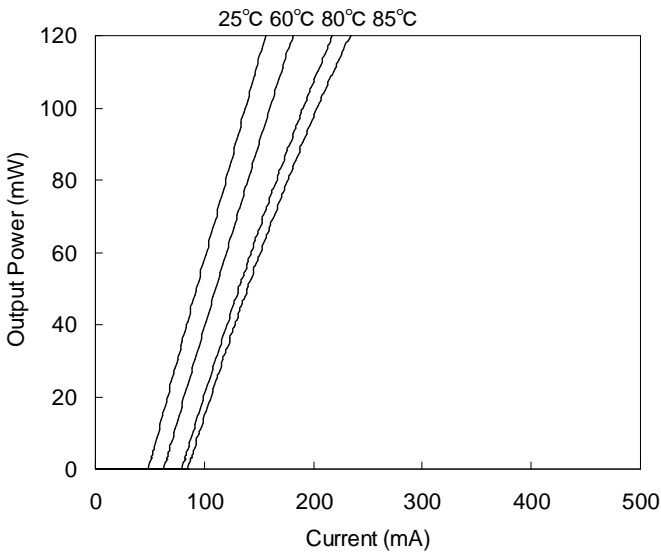
T=25°C, CW, Po=90 mW

Item	Symbol	Min.	Typ.	Max.	Unit	Condition	
Threshold current	I <sub>th</sub>	35	50	70	mA		
Operating current	I <sub>op</sub>	110	128	165	mA		
Operating voltage	V <sub>op</sub>	2.0	2.4	3.0	V		
Wavelength	$\lambda$	656	661	665	nm		
Beam Divergence	Parallel	$\theta_h$	7.5	9.0	13.0	deg	FWHM
	Perpendicular	$\theta_v$	13.0	15.0	19.5	deg	FWHM

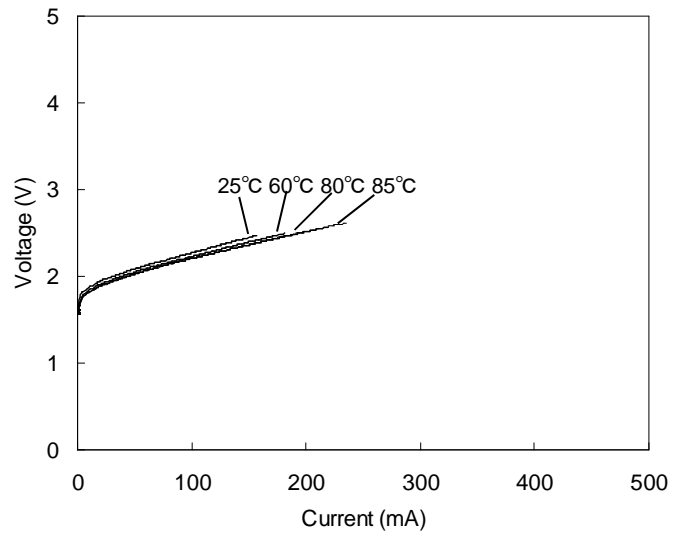
FWHM: Full width at half maximum

Typical Characteristics

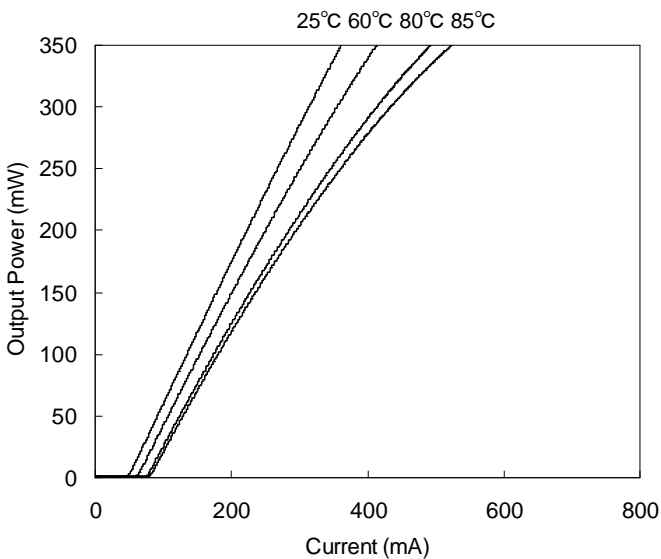
Output Power vs Current (CW)



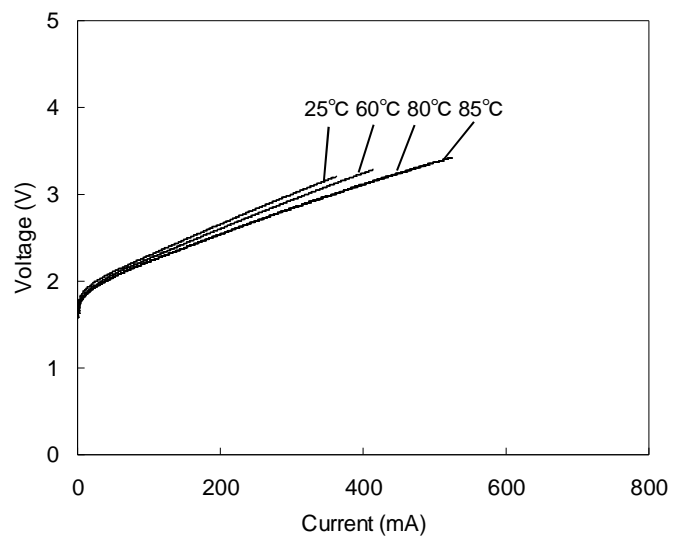
Voltage vs Current (CW)



Output Power vs Current (Pulse)

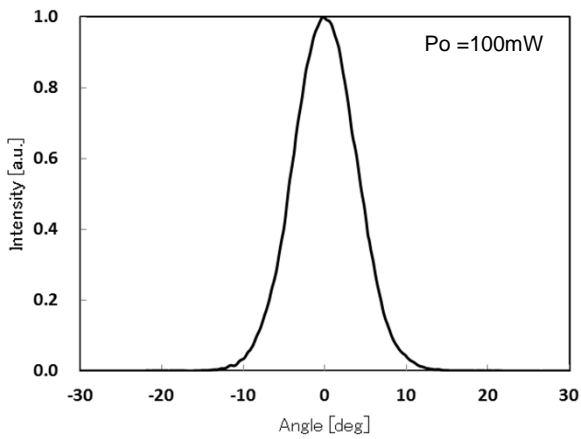


Voltage vs Current (Pulse)

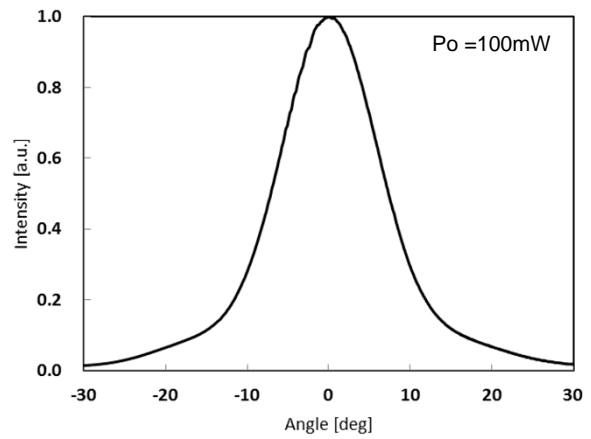


Typical Characteristics

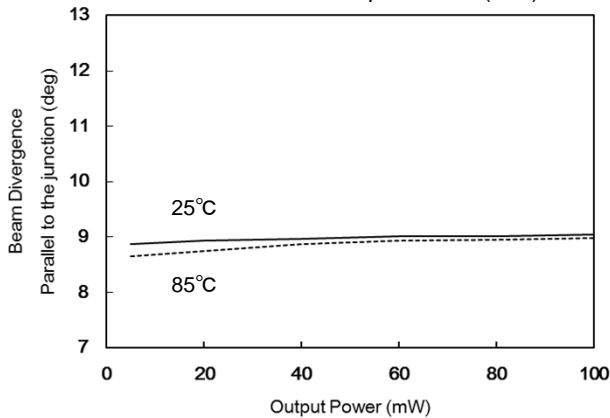
Beam Divergence  
Parallel to the Junction (CW)



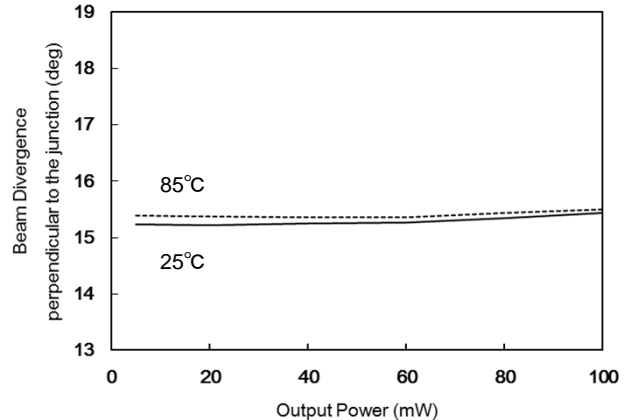
Beam Divergence  
Perpendicular to the Junction (CW)



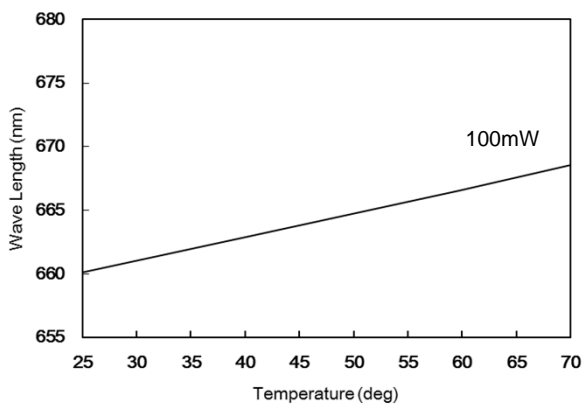
Beam Divergence of Parallel  
to the Junction vs Output Power (CW)



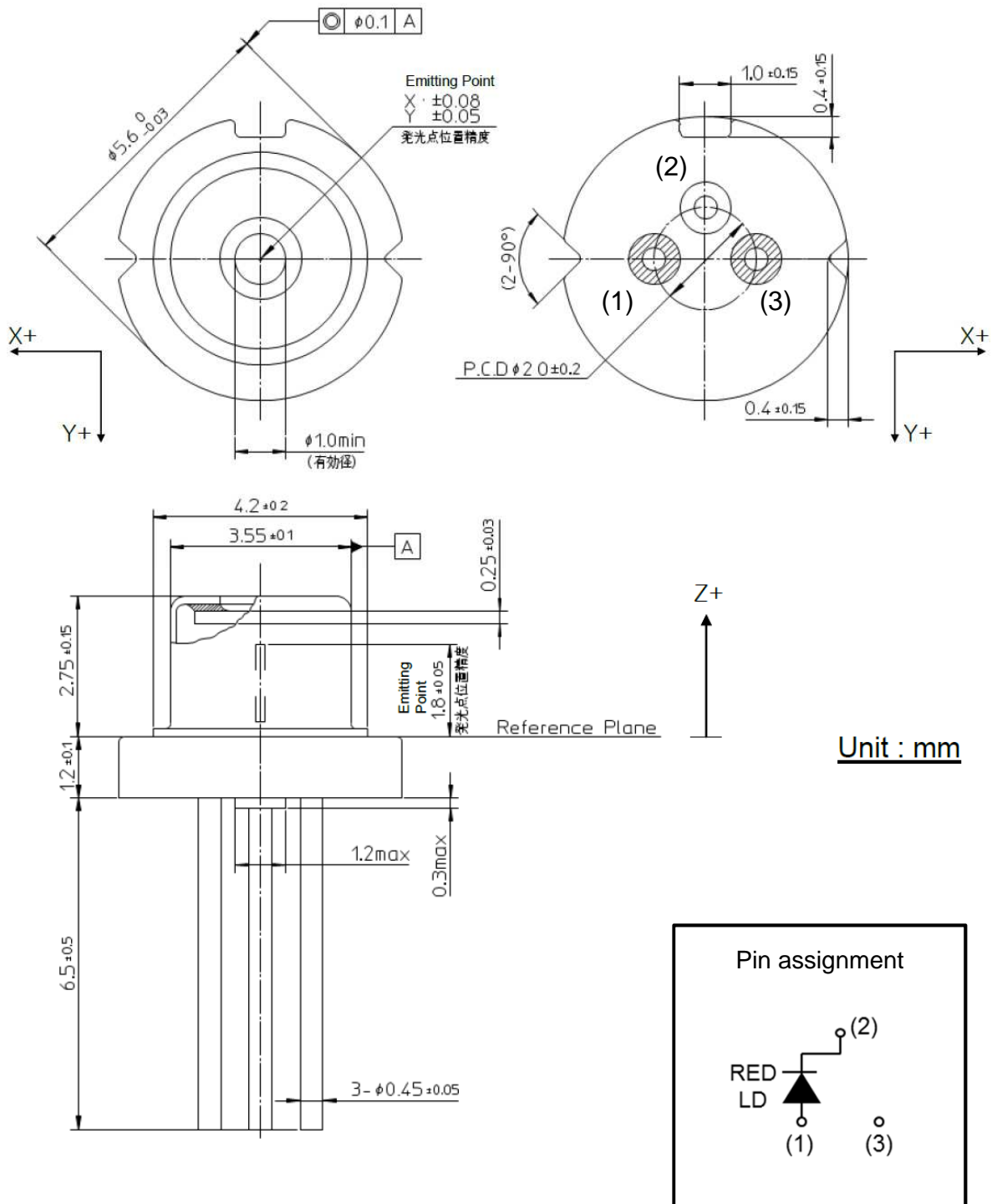
Beam Divergence of Perpendicular  
to the Junction vs Output Power (CW)



Wavelength vs Temperature (CW)



Package Dimensions



Note)

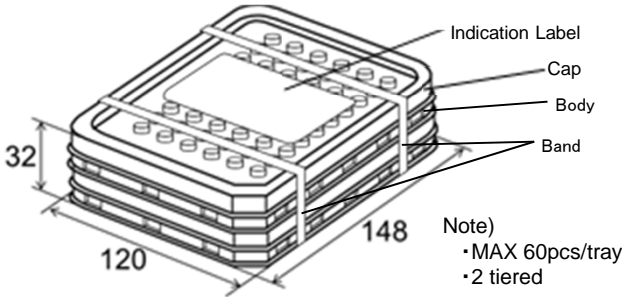
1. X-Y tolerance of lead is specified on the package bottom plane.

### Packing Specifications

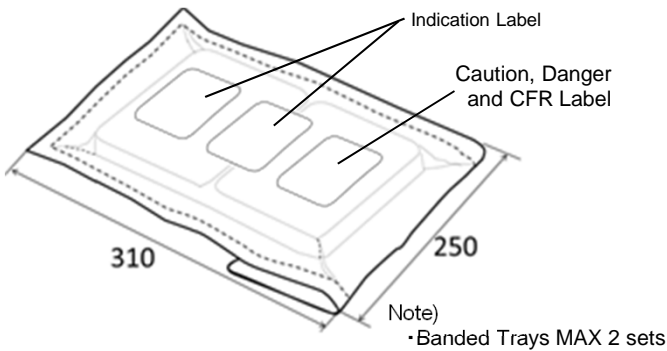
1 Packing Material

1.1 Tray

Material: PS Conductive (Black)

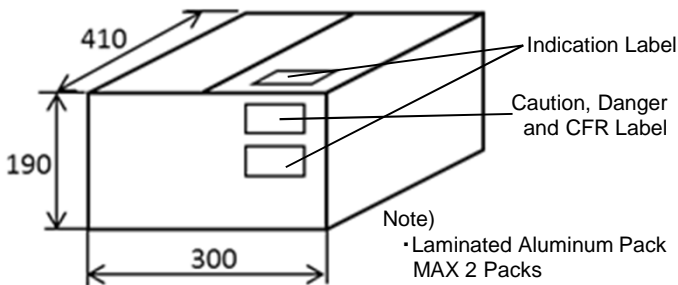


1.2 Laminated Aluminum Pack



1.3 Packing Case

Material: Corrugated fiber board



※As for label indication except ①(Order person part number), ②(Order person part number and Quantity), ③(Serial number and Corporate code), and ④(Quantity), the information only for our process control. Therefore, revision might be done for improvement without notice.

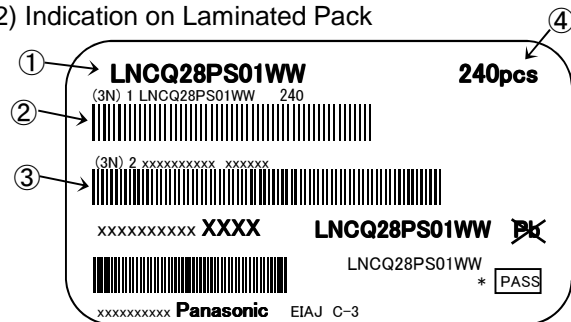
### 2 Packaging Quantity

Form	Quantity	Contents
Tray	n=60	--
Laminated Aluminum Pack	n=240	Tray: 4
Packing Case	n=240 to 1920	Aluminum Pack:1 to 8

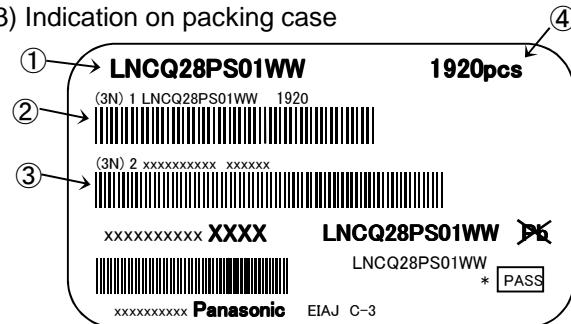
### 1) Indication on Top Tray



### 2) Indication on Laminated Pack



### 3) Indication on packing case



## Warning

### ■ Laser class

This product is ranked "Class IIIb laser" according to IEC60825-1 and JIS standard 6802 "Laser Product Emission Safety Standards," so that safety protection is necessary when laser beam is radiated.

## Cautions

### ■ TO-56 CAN packaged laser diode

This product uses a TO-56 CAN package to ensure versatile use.

### ■ Prevention of Electrostatic discharge (ESD) and surge stress

Semiconductor laser diode is a device sensitive to ESD and surge, so that sufficient cautions are needed. If electrostatic discharge is applied to a laser diode, intensive light emission may occur instantaneously, leading to the potential for catastrophic damage in the laser diode or degradation of the laser diode in a short time.

Therefore, taking all possible measures against ESD and surge for usage of CAN packaged laser diode is strongly requested.

### ■ Heat sink design

As case temperature becomes higher, the life of semiconductor laser diode becomes shorter. So appropriate heat dissipation design is required. Especially it is effective to make a thermal connection to the highly thermally conductive heat sink at the base plate of a TO56 package.

### ■ Precautions for soldering

Excess heating to laser diode package during soldering may affect eutectic solder and/or laser diode itself. Soldering must be done as quickly as possible with controlling the heating temperature. Lead(terminal) soldering with appropriate cooling time is strongly recommended. Also, soldering position of lead(terminal) is recommended to be more than 2mm away from the package body.

- Soldering temperature: below 350°C
- Heating period: within 3 s
- Soldering position: 2mm away from the package body



# Caution for Safety



**DANGER**

Do not touch or look into the laser beam directly.

The laser beam may cause injury to the eye or skin, or loss of eyesight.

## Request for your special attention and precautions in using the technical information and semiconductors described in this book

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